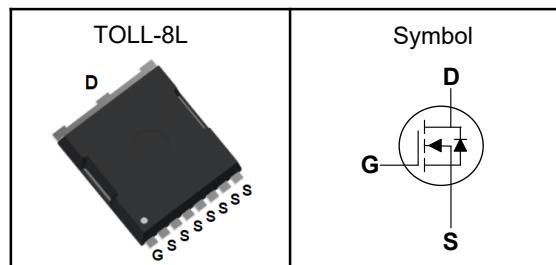


N-Channel Enhancement Mode MOSFET

Features

- High Speed Power Switching
- Reliable and Rugged
- ROHS Compliant
- 100% Avalanche Tested

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

V_{DSS}	40	V
$R_{DS(ON)-Typ}$	0.84	$\text{m}\Omega$
I_D	400	A

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
V_{DSS}	Drain-Source Voltage	40	V
V_{GSS}	Gate-Source Voltage	± 20	V
T_J	Maximum Junction Temperature	-55 to 175	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 175	$^\circ\text{C}$
$I_{DM}^{\text{(1)}}$	Pulse Drain Current Tested	1600	A
I_D	Continuous Drain Current	400	A
P_D	Maximum Power Dissipation	600	W
E_{AS}	Avalanche Energy, Single pulse	1352	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	33	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Thermal Resistance-Junction to Case	0.4	$^\circ\text{C}/\text{W}$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C .

Note ③ : Surface Mounted on 1in^2 FR-4 board with 1oz.

N-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

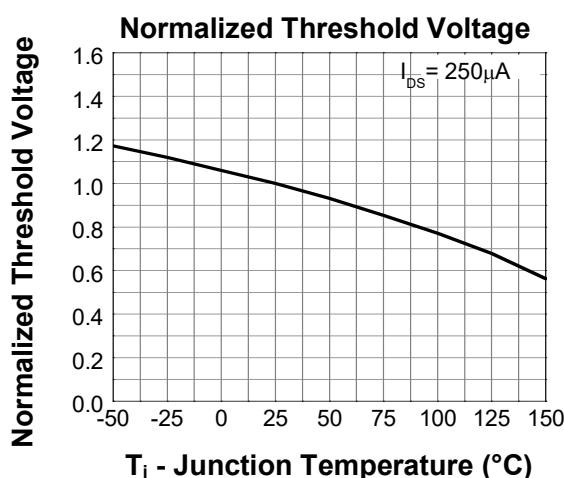
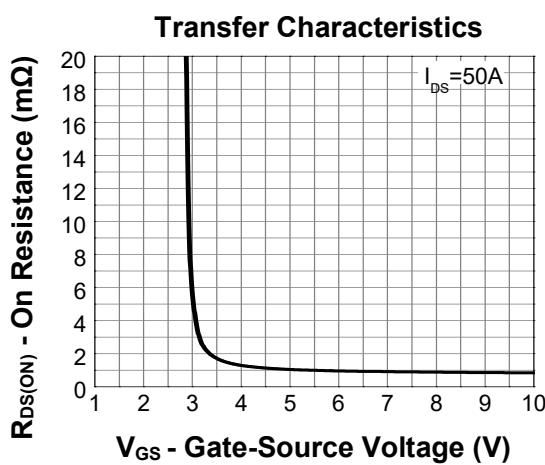
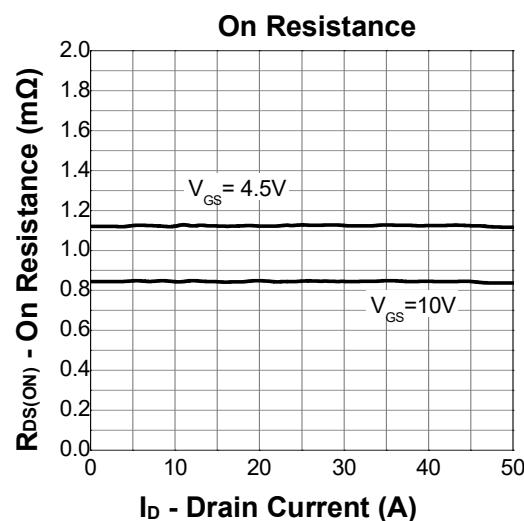
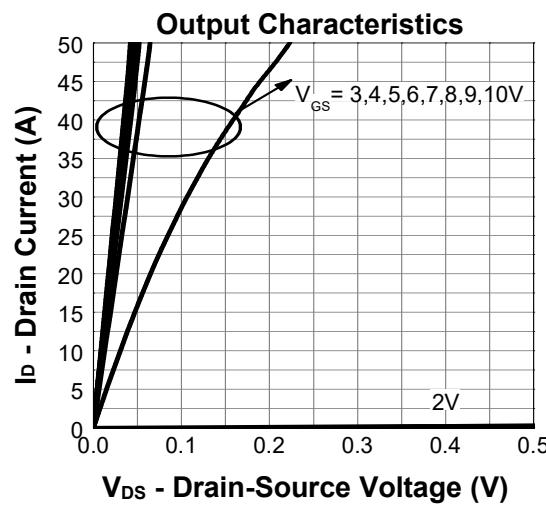
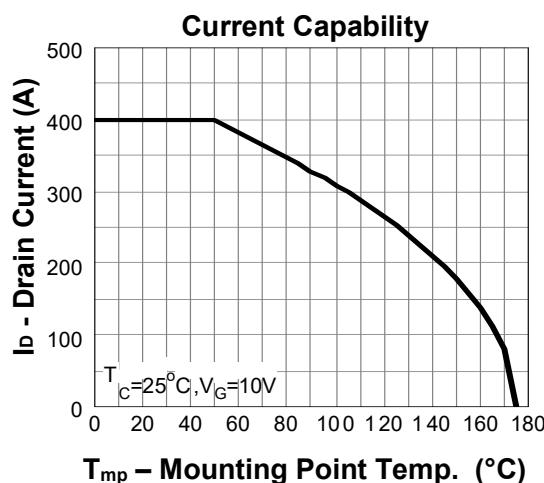
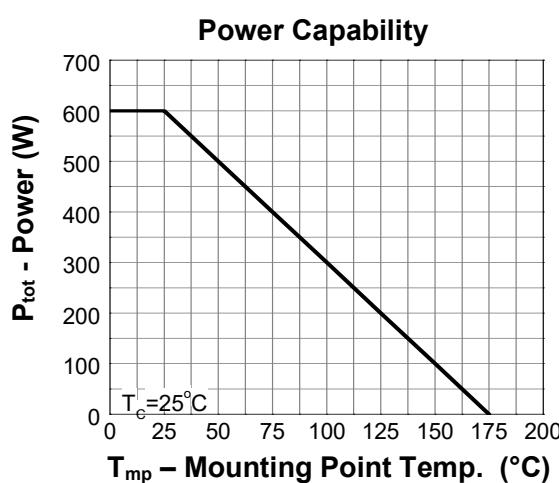
Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\mu\text{A}$	40	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=32\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$	---	---	1	μA
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}$, $\text{I}_D=250\mu\text{A}$	1	---	2	V
I_{GSS}	Gate Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$\text{R}_{\text{DS(ON)}}$	Drain-Source On-state Resistance	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=50\text{A}$	---	0.84	0.95	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=20\text{A}$	---	1.1	1.25	$\text{m}\Omega$
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=20\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, Freq.=1MHz	---	8296	---	pF
C_{oss}	Output Capacitance		---	3294	---	
C_{rss}	Reverse Transfer Capacitance		---	55	---	
$\text{T}_{\text{d(on)}}$	Turn-on Delay Time	$\text{V}_{\text{DS}}=20\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=50\text{A}$, $\text{R}_G=4.5\Omega$	---	19	---	nS
T_r	Turn-on Rise Time		---	84	---	
$\text{T}_{\text{d(off)}}$	Turn-off Delay Time		---	153	---	
T_f	Turn-off Fall Time		---	126	---	
Q_g	Total Gate Charge	$\text{V}_{\text{DS}}=20\text{V}$, $\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=50\text{A}$	---	148	---	nC
Q_{gs}	Gate-Source Charge		---	26	---	
Q_{gd}	Gate-Drain Charge		---	25	---	
Source-Drain Characteristics						
V_{SD}	Diode Forward Voltage	$\text{I}_S=50\text{A}$, $\text{V}_{\text{GS}}=0\text{V}$	---	---	1.3	V
t_{rr}	Reverse Recovery Time	$\text{I}_F=50\text{A}$, $\text{V}_{\text{GS}}=0\text{V}$, $d\text{I}/dt=100\text{A}/\mu\text{s}$	---	97	---	nS
			---	162	---	nC

Note ④: Pulse test (pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$).

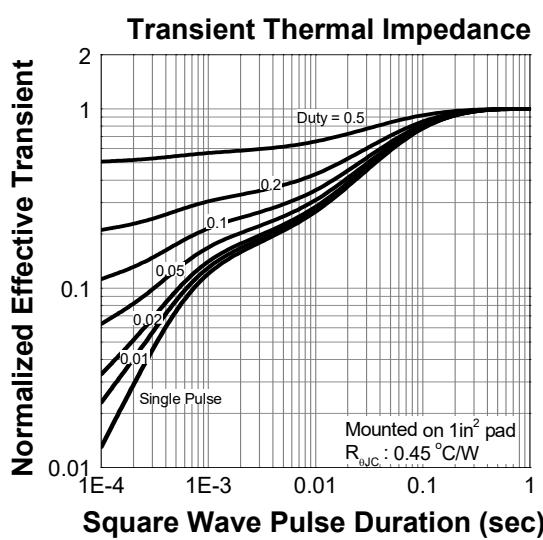
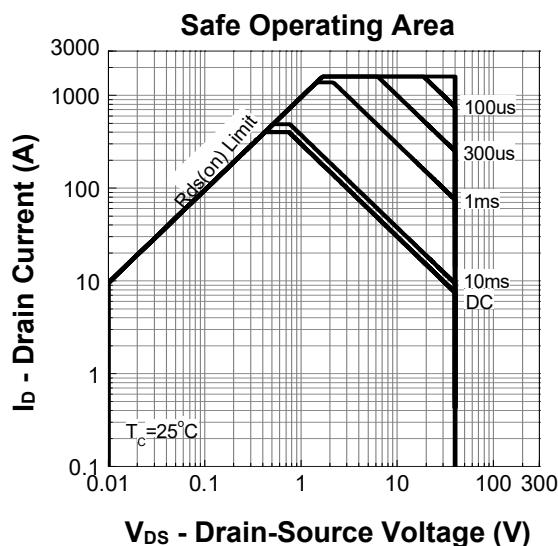
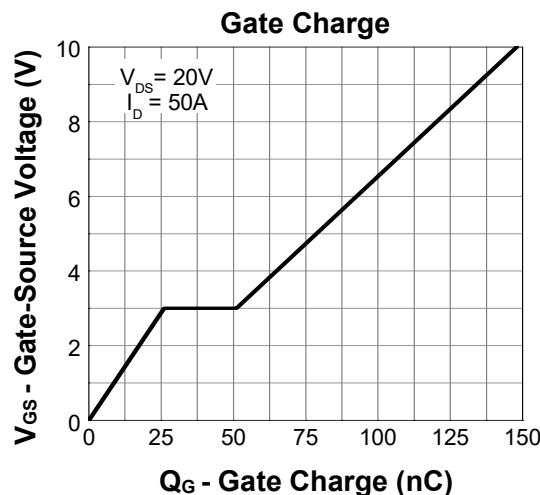
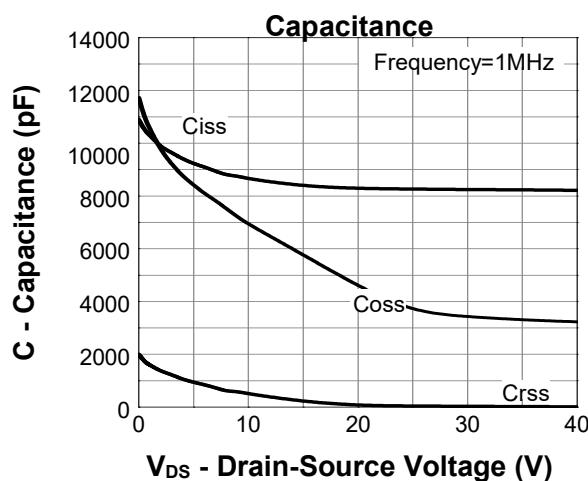
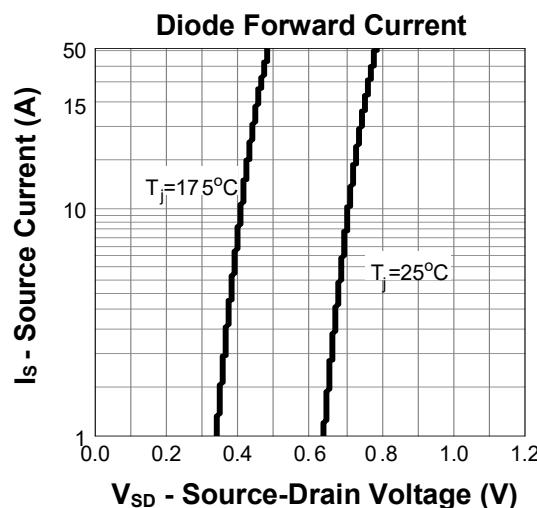
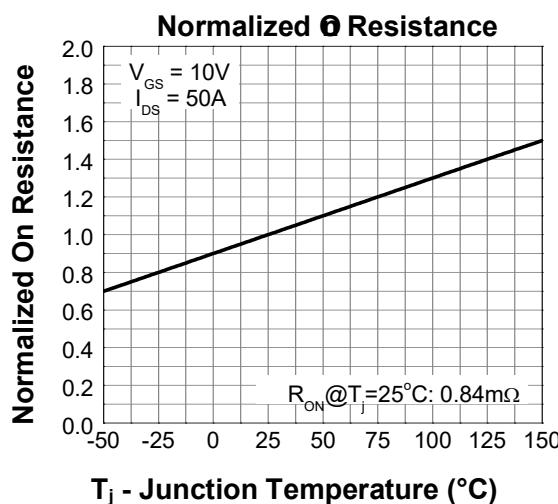
Note ⑤ : Guaranteed by design, not subject to production testing.

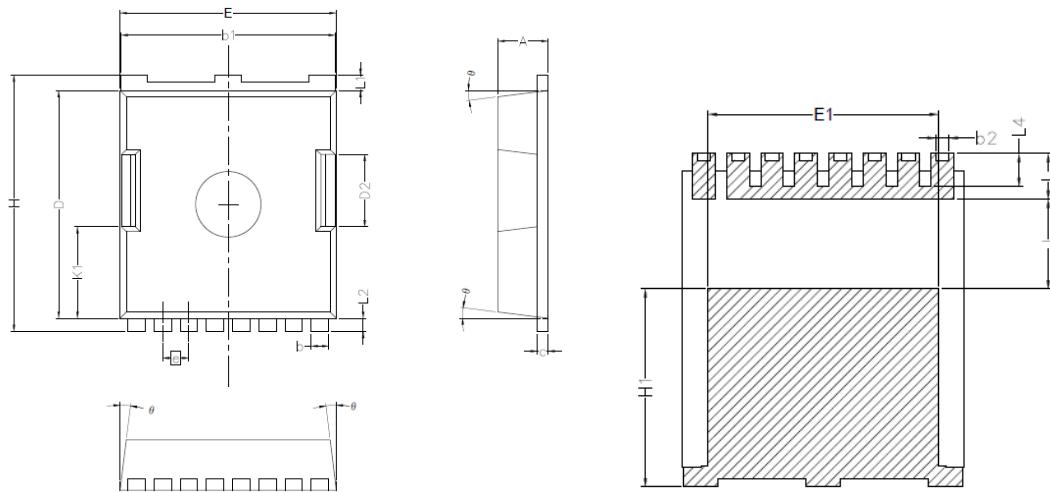
N-Channel Enhancement Mode MOSFET

Typical Characteristics



N-Channel Enhancement Mode MOSFET



N-Channel Enhancement Mode MOSFET
TOLL-8L Package Outline Data


Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	2.20	2.40
b	0.90	0.90
b1	9.70	9.90
b2	0.42	0.50
c	0.40	0.60
D	10.28	10.58
D2	3.10	3.50
E	9.70	10.10
E1	7.90	8.30
e	1.20BSC	
H	11.48	11.88
H1	6.75	7.15
N	8	
J	3.00	3.30
K1	3.98	4.38
L	1.40	1.80
L1	0.60	0.80
L2	0.50	0.70
L4	1.00	1.30
θ	4°	10°